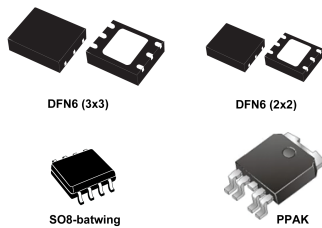


1.2 A low quiescent current LDO with reverse current protection



Features

- Input voltage from 1.6 to 5.5 V
- Very low-dropout voltage (300 mV typ. at 1 A load)
- Low quiescent current (35 μ A typ. at no-load, 1 μ A max. in off mode)
- Output voltage tolerance: $\pm 2.0\%$ at 25 °C
- 1.2 A guaranteed output current
- Wide range of output voltages available on request: 0.8 V to 5 V with 50 mV step and adjustable
- Logic-controlled electronic shutdown
- Compatible with ceramic capacitor $C_{OUT} = 1 \mu$ F
- Internal current and thermal limit
- Available in DFN6 (2x2), DFN6 (3x3) mm, SO8-batwing and PPAK packages
- Temperature range: -40 °C to 125 °C
- Reverse current protection
- Output discharge function (optional)

Applications

- Consumer
- Computer
- Battery-powered systems
- Low voltage point-of-load
- USB-powered devices

Maturity status link

[LDL112](#)

Description

The **LDL112** is a low-dropout linear regulator, which can provide a maximum current of 1.2 A, with a typical dropout voltage of 300 mV.

It is stabilized with a ceramic capacitor on the output.

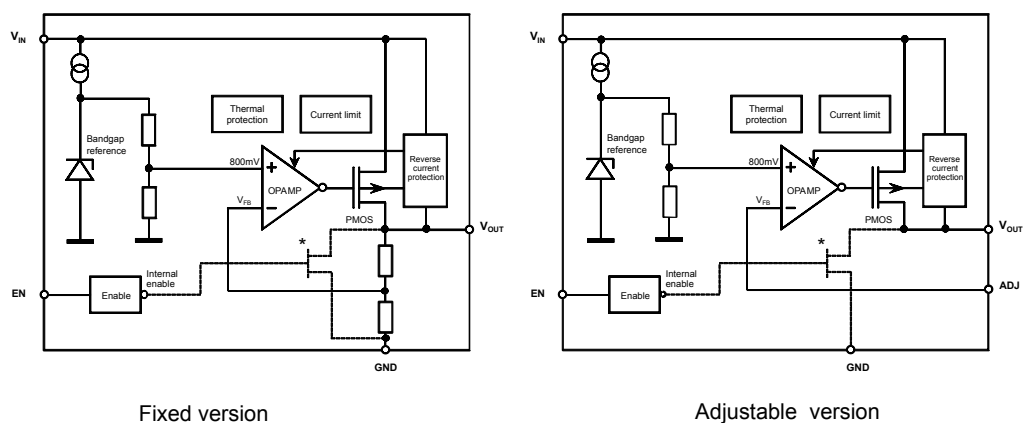
The very low drop voltage, low quiescent current and reverse current protection features make it suitable for low power battery-powered applications.

The enable logic control function puts the **LDL112** in shutdown mode allowing a total current consumption lower than 1 μ A.

The device is equipped with current limit and thermal protection.

1 Diagram

Figure 2. Block diagram



AM14036V1

Note: (*) The output discharge function is optional.

2 Pin configuration

Figure 3. Pin connection DFN6 (3x3) and DFN6 (2x2) (top view)

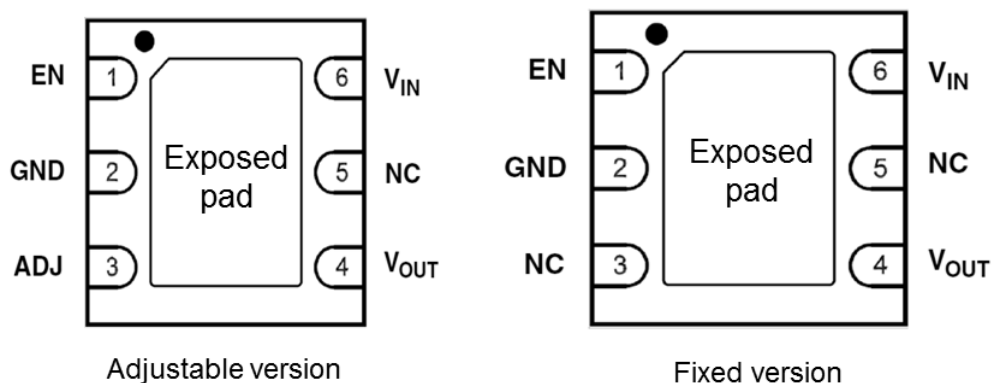
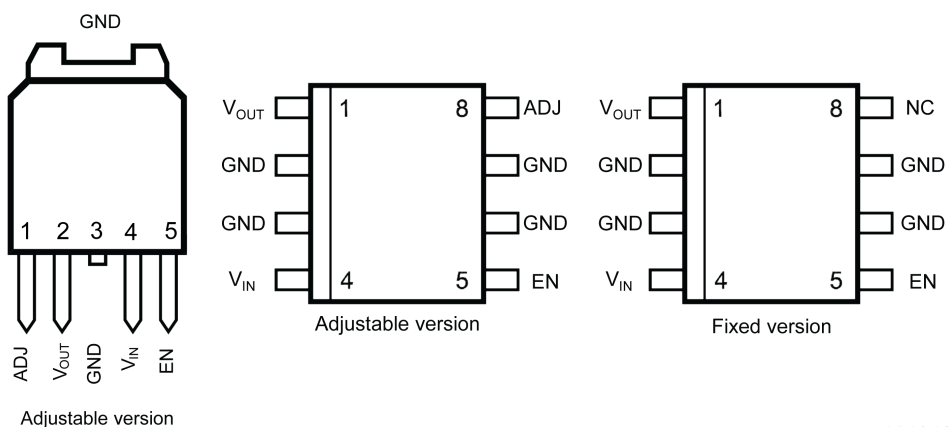


Figure 4. Pin connection PPAK and SO8 (top view)



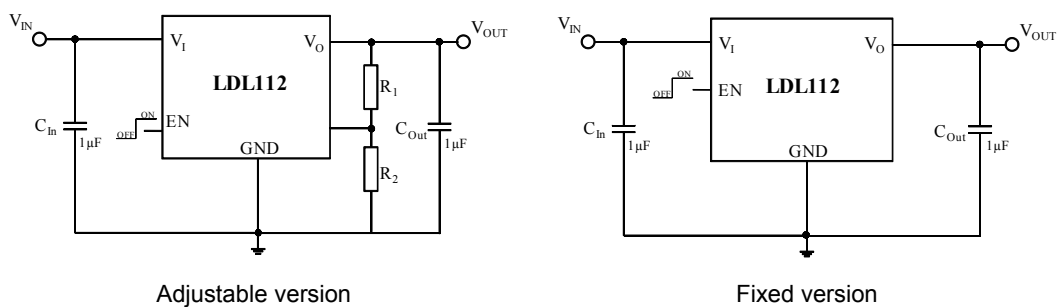
AM14038V1

Table 1. Pin description

Symbol	Function
V_{IN}	LDO input voltage
GND	Common ground
EN	Enable pin logic input: low = shutdown, high = active. Don't leave this pin floating
ADJ	Adjustable pin (on adjustable version)
V_{OUT}	LDO output voltage
Exposed pad	Must be connected to GND
NC	Not connected

3 Typical application

Figure 5. Typical application circuits



AM14039V1

4 Maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{IN}	DC input voltage	- 0.3 to 7	V
V_{OUT}	DC output voltage	- 0.3 to $V_I + 0.3$	V
V_{EN}	Enable input voltage	- 0.3 to $V_I + 0.3$	V
V_{ADJ}	ADJ pin voltage	2	V
I_{OUT}	Output current	Internally limited	mA
P_D	Power dissipation	Internally limited	mW
T_{STG}	Storage temperature range	- 65 to 150	°C
T_{OP}	Operating junction temperature range	- 40 to 125	°C

Note: Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. All values are referred to GND.

Table 3. Thermal data

Symbol	Parameter	DFN6 (3x3)	DFN6 (2x2)	SO8	PPAK	Unit
R_{thJA}	Thermal resistance junction-ambient	55	65	55 ⁽¹⁾	100	°C/W
R_{thJC}	Thermal resistance junction-case	10	15	20	8	°C/W

1. Considering 6 cm² of copper board heatsink.

5 Electrical characteristics

$T_J = 25\text{ }^{\circ}\text{C}$, $V_{IN} = V_{OUT(NOM)} + 0.5\text{ V}$ (for $V_{OUT(NOM)} \leq 1\text{ V}$, $V_{IN} = 2.1\text{ V}$), $C_{IN} = C_{OUT} = 1\text{ }\mu\text{F}$, $I_{OUT} = 5\text{ mA}$, $V_{EN} = V_{IN}$, unless otherwise specified.

Table 4. LDL112 electrical characteristics (fixed version)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IN}	Operating input voltage		1.6		5.5	V
V_{OUT}	V_{OUT} accuracy	$I_{OUT} = 5\text{ mA}$, $T_J = 25\text{ }^{\circ}\text{C}$	-2.0		2.0	%
		$I_{OUT} = 5\text{ mA}$, $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$	-3.0		3.0	%
ΔV_{OUT}	Static line regulation ⁽¹⁾	$V_{OUT(NOM)} + 0.5\text{ V} < V_{IN} \leq 5.5\text{ V}$ ⁽²⁾		0.05	0.1	%/V
ΔV_{OUT}	Static load regulation	$I_{OUT} = 0\text{ mA}$ to 1.2 A , $V_{IN} > 2.1\text{ V}$		15	30	mV
V_{DROP}	Dropout voltage ⁽³⁾	$I_{OUT} = 1\text{ A}$, $V_{OUT} = 3.3\text{ V}$		300		mV
		$I_{OUT} = 1.2\text{ A}$, $V_{OUT} = 3.3\text{ V}$ $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$		350	600	
e_N	Output noise voltage	10 Hz to 100 kHz, $I_{OUT} = 10\text{ mA}$ $V_{OUT} = 3.3\text{ V}$		135		μV_{RMS}
SVR	Supply voltage rejection	$V_{IN} = V_{OUT(NOM)} + 0.5\text{ V} \pm V_{RIPPLE}$ ⁽²⁾ $V_{RIPPLE} = 0.2\text{ V}$ frequency = 1 kHz $I_{OUT} = 10\text{ mA}$		57		dB
I_Q	Quiescent current	$I_{OUT} = 0\text{ mA}$, $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$		35	70	μA
		$I_{OUT} = 1.2\text{ A}$, $V_{OUT(NOM)} + 1\text{ V}$, $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$ ⁽²⁾		250	400	
		V_{IN} input current in off mode: $V_{EN} = \text{GND}$		0.1	1	
I_{SC}	Short-circuit current	$R_L = 0$, $V_{IN} > 2.1\text{ V}$	1.4	2		A
V_{EN}	Enable input logic low	$V_{IN} = V_{OUT(NOM)} + 0.5\text{ V}$ to 5.5 V , $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$ ⁽²⁾			0.35	V
	Enable input logic high	$V_{IN} = V_{OUT(NOM)} + 0.5\text{ V}$ to 5.5 V , $-40\text{ }^{\circ}\text{C} < T_J < 125\text{ }^{\circ}\text{C}$ ⁽²⁾	1.4			
I_{EN}	Enable pin input current	$V_{EN} = V_{IN}$			100	nA
T_{SHDN}	Thermal shutdown			165		$^{\circ}\text{C}$
	Hysteresis			20		
C_{OUT}	Output capacitor	Capacitance (see Section 7 Typical performance characteristics)	1		10	μF

1. Not applicable for $V_{out(nom)} > 4.5\text{ V}$.

2. For V_{OUTNOM} lower than or equal to 1 V, $V_{IN} = 2.1\text{ V}$.

3. Dropout voltage is the input-to-output voltage difference at which the output voltage is 100 mV below its nominal value.

$T_J = 25\text{ °C}$, $V_{IN} = 2.1\text{ V}$, $C_{IN} = C_{OUT} = 1\text{ }\mu\text{F}$, $I_{OUT} = 5\text{ mA}$, $V_{EN} = V_{IN}$, unless otherwise specified.

Table 5. LDL112 electrical characteristics (adjustable version)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IN}	Operating input voltage		1.6		5.5	V
V_{ADJ}	V_{ADJ} accuracy	$I_{OUT} = 5\text{ mA}$, $T_J = 25\text{ °C}$	784	800	816	mV
		$I_{OUT} = 5\text{ mA}$, $-40\text{ °C} < T_J < 125\text{ °C}$	-3.0		3.0	%
ΔV_{OUT}	Static line regulation ⁽¹⁾	$2.1\text{ V} \leq V_{IN} \leq 5.5\text{ V}$, $I_{OUT} = 1\text{ mA}$ ⁽²⁾		0.05	0.1	%/V
ΔV_{OUT}	Static load regulation	$I_{OUT} = 0\text{ mA}$ to 1.2 A , $V_{IN} > 2.1\text{ V}$		6	20	mV
V_{DROP}	Dropout voltage ⁽³⁾	$I_{OUT} = 1\text{ A}$, $V_{OUT} = 3.3\text{ V}$		300		mV
		$I_{OUT} = 1.2\text{ A}$, $V_{OUT} = 3.3\text{ V}$		350	600	
		$-40\text{ °C} < T_J < 125\text{ °C}$				
e_N	Output noise voltage	10 Hz to 100 kHz, $I_{OUT} = 10\text{ mA}$		60		μV_{RMS}
I_{ADJ}	Adjust pin current			0.130	1	μA
SVR	Supply voltage rejection	$V_{IN} = V_{OUTNOM} + 0.5\text{ V} \pm V_{RIPPLE}$ $V_{RIPPLE} = 0.2\text{ V}$, freq. = 1 kHz, $I_{OUT} = 10\text{ mA}$ ⁽²⁾		53		dB
I_Q	Quiescent current	$I_{OUT} = 0\text{ mA}$, $-40\text{ °C} < T_J < 125\text{ °C}$		35	70	μA
		$I_{OUT} = 1.2\text{ A}$, $2.1\text{ V} < V_{IN} < 5.5\text{ V}$, $-40\text{ °C} < T_J < 125\text{ °C}$		240	400	
		V_{IN} input current in off mode: $V_{EN} = \text{GND}$		0.1	1	
I_{SC}	Short-circuit current	$R_L = 0$, $V_{IN} > 2.1\text{ V}$	1.4	2		A
V_{EN}	Enable input logic low	$V_{IN} = 2\text{ V}$ to 5.5 V , $-40\text{ °C} < T_J < 125\text{ °C}$ ⁽²⁾		0	0.35	V
	Enable input logic high	$V_{IN} = 2\text{ V}$ to 5.5 V , $-40\text{ °C} < T_J < 125\text{ °C}$ ⁽²⁾	1.4			
I_{EN}	Enable pin input current	$V_{EN} = V_{IN}$			100	nA
T_{SHDN}	Thermal shutdown			165		$^{\circ}\text{C}$
	Hysteresis			20		
C_{OUT}	Output capacitor	Capacitance (see Section 7 Typical performance characteristics)	1		10	μF

1. Not applicable for $V_{out(nom)} > 4.5\text{ V}$.

2. For V_{OUT} lower than or equal to 1 V , $V_{IN} = 2.1\text{ V}$.

3. Dropout voltage is the input-to-output voltage difference at which the output voltage is 100 mV below its nominal value.

6 Application information

6.1 Thermal and short-circuit protections

The LDL112 is self-protected from short-circuit condition and overtemperature. When the output load is higher than the one supported by the device, the output current increases until the limit of typically 2 A is reached, at this point the current is kept constant even when the load impedance is zero.

Thermal protection acts when the junction temperature reaches 165 °C, therefore the IC shuts down. As soon as the junction temperature falls again below the thermal hysteresis value the device starts working again.

In order to calculate the maximum power that the device can dissipate, keeping the junction temperature below the T_{OP} , the following formula is used:

Equation 1

$$P_{DMAX} = (125 - T_{AMB}) / R_{THJA}$$

6.2 Output voltage setting for ADJ version

In the adjustable version, the output voltage can be set from 0.8 V up to the input voltage minus the voltage drop across the pass transistor (dropout voltage), by connecting a resistor divider between the ADJ pin and the output, thus allowing remote voltage sensing.

The resistor divider could be selected by the following equation:

Equation 2

$$V_{OUT} = V_{ADJ} (1 + R1 / R2), \text{ with } V_{ADJ} = 0.8 \text{ V (typ.)}$$

It is recommended to use resistors with values in the range of 10 kΩ to 50 kΩ. Lower values can also be suitable, but current consumption increases.

6.3 Reverse current protection

The device avoids the reverse current to flow from output to input during any operating condition (with enable pin in high or low status). The reverse current protection acts in particular during fast turning on/off operations or when another power supply (with higher voltage than the input one) is connected to the output port. If a power supply with lower voltage than the LDO output voltage is connected to V_{OUT} pin, LDO enters the current protection status, causing high power dissipation.

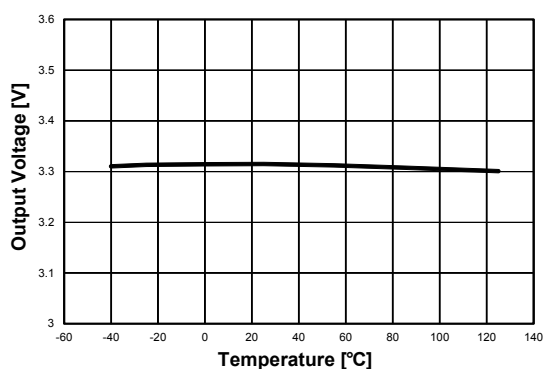
In the application, the LDL112 reverse current protection acts in the following cases:

1. **Off-state, EN pin is at GND level, $V_{OUT} > [V_{IN} + 100 \text{ mV}]$.** In this case the device power pass element (MOSFET) is off, the bulk and gate are switched to V_{OUT} and therefore all possible current paths from V_{OUT} to V_{IN} are interrupted.
2. **On-state, EN pin is at high level and $V_{OUT} > V_{OUT(nominal)}$.** In this condition, V_{OUT} is higher than the nominal level, so the device op-amp works in open loop and the power element is off. V_{GS} is zero, the bulk and gate are switched to V_{OUT} (where $V_{OUT} > [V_{IN} + 100 \text{ mV}]$) therefore all possible current paths from V_{OUT} to V_{IN} are interrupted.
3. **On-state, EN pin is at high level and $V_{OUT} < V_{OUT(nominal)}$.** In this condition V_{OUT} is lower than the nominal level, so the op-amp works in open loop with the power MOSFET on. V_{GS} is maximal so the power channel conducts with very low $R_{DS(on)}$. When $V_{OUT} > V_{IN}$ the current can flow from V_{OUT} to V_{IN} until the condition $V_{OUT} > (V_{IN} + 100 \text{ mV})$ is reached.

7 Typical performance characteristics

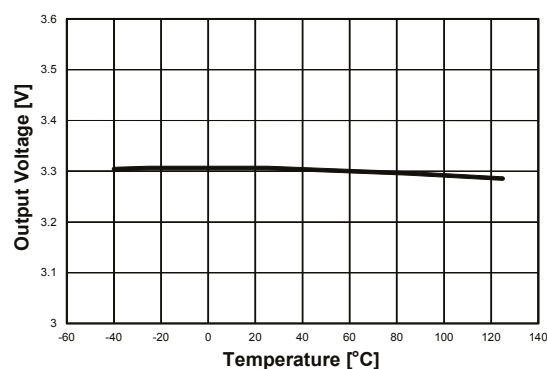
($C_{IN} = C_{OUT} = 1 \mu F$, V_{EN} to V_{IN} , $T = 25^\circ C$ unless otherwise specified)

Figure 8. Output voltage vs. temperature
($V_{OUT} = 3.3 V$, $I_{OUT} = 5 mA$)



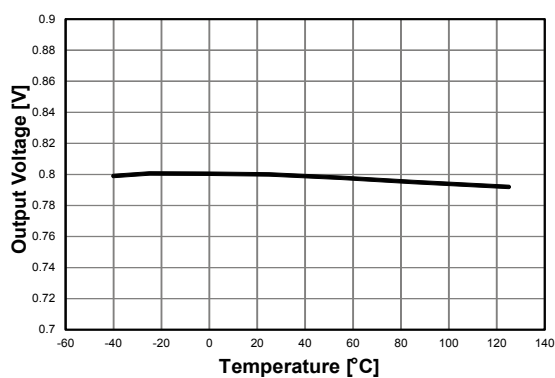
$V_{IN}=3.8V$, $I_{OUT}=5mA$, $V_{OUT}=3.3V$ AM14040V1

Figure 9. Output voltage vs. temperature
($V_{OUT} = 3.3 V$, $I_{OUT} = 1.2 A$)



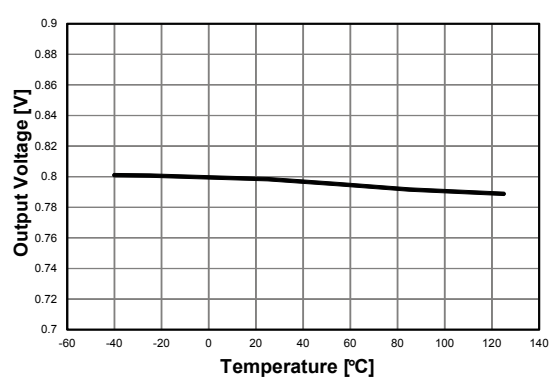
$V_{IN}=3.8V$, $I_{OUT}=1.2A$, $V_{OUT}=3.3V$ AM14041V1

Figure 10. Output voltage vs. temperature
($V_{OUT} = V_{ADJ}$, $I_{OUT} = 5 mA$)



$V_{IN}=1.6V$, $I_{OUT}=5mA$, $V_{OUT}=V_{ADJ}$ AM14042V1

Figure 11. Output voltage vs. temperature
($V_{OUT} = V_{ADJ}$, $I_{OUT} = 1.2 A$)



$V_{IN}=2V$, $I_{OUT}=1.2A$, $V_{OUT}=V_{ADJ}$ AM14043V1

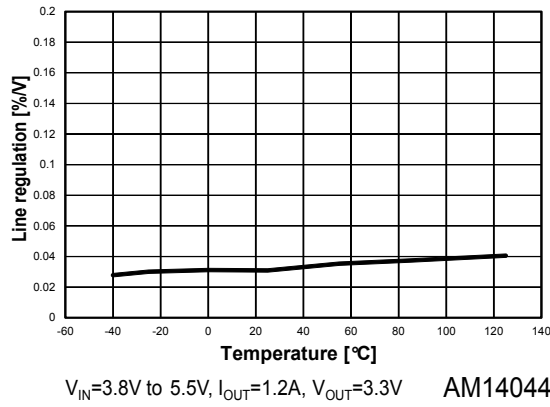
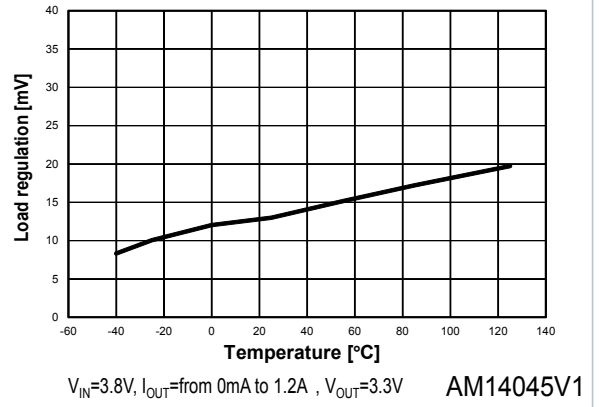
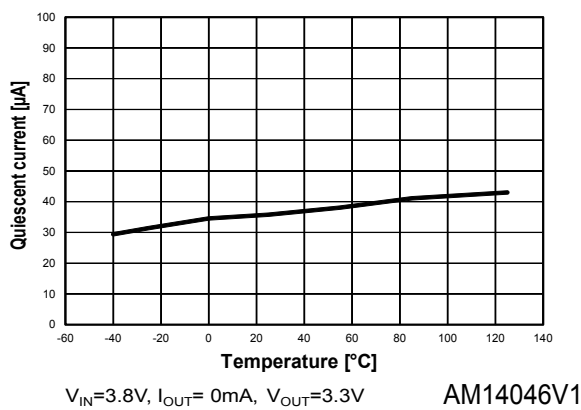
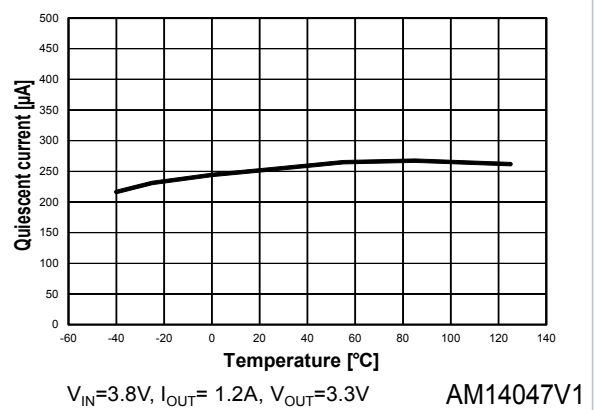
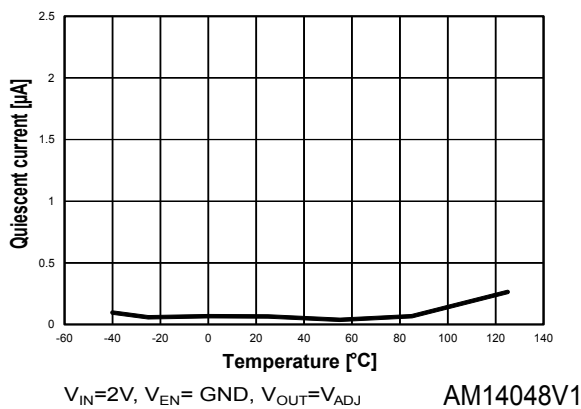
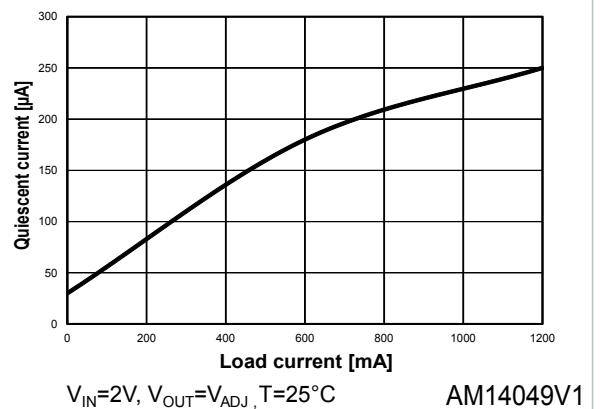
Figure 12. Line regulation vs. temperature

Figure 13. Load regulation vs. temperature

Figure 14. Quiescent current vs. temperature ($I_{OUT} = 0$ mA)

Figure 15. Quiescent current vs. temperature ($I_{OUT} = 1.2$ A)

Figure 16. Shutdown current vs. temperature

Figure 17. Quiescent current vs. load current


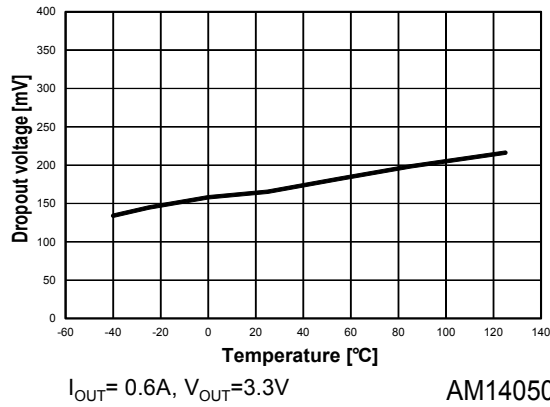
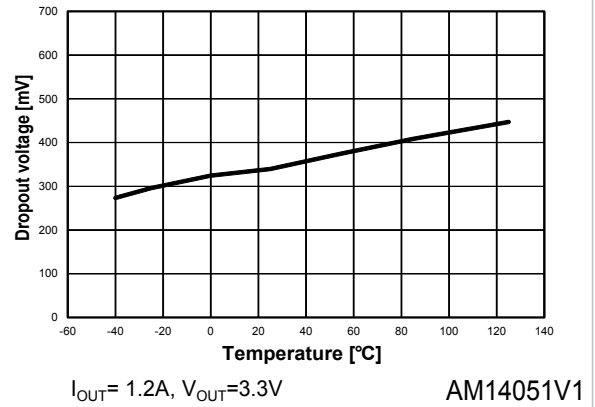
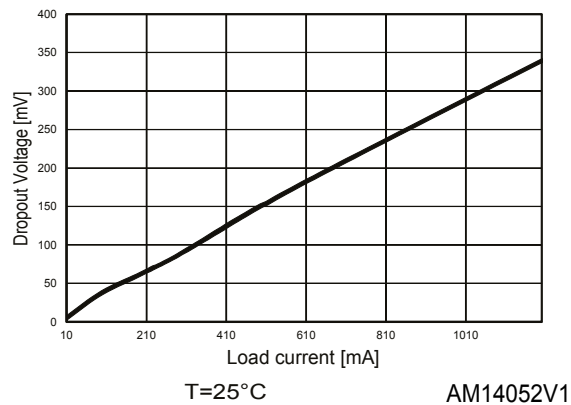
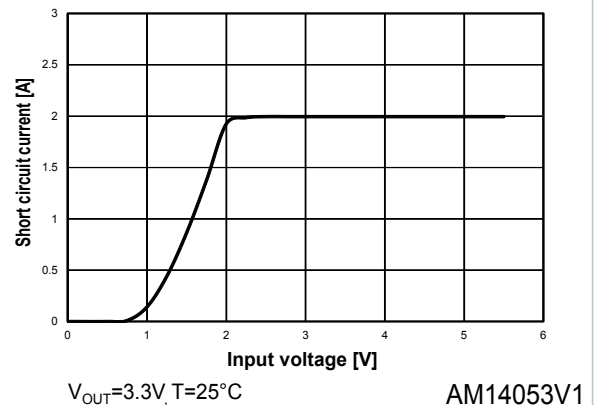
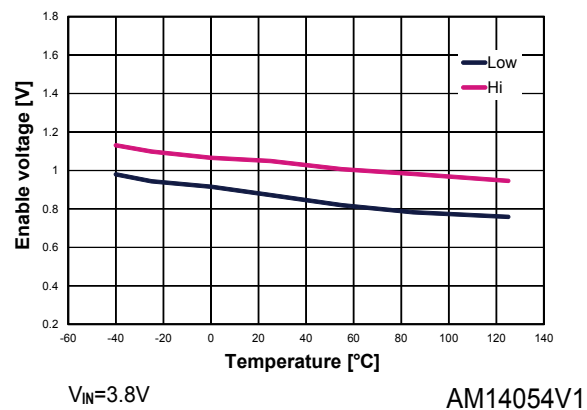
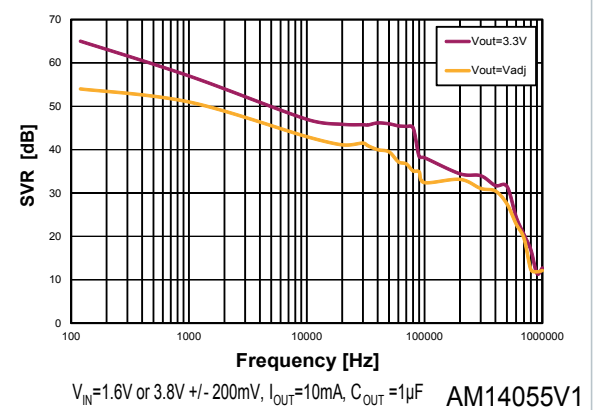
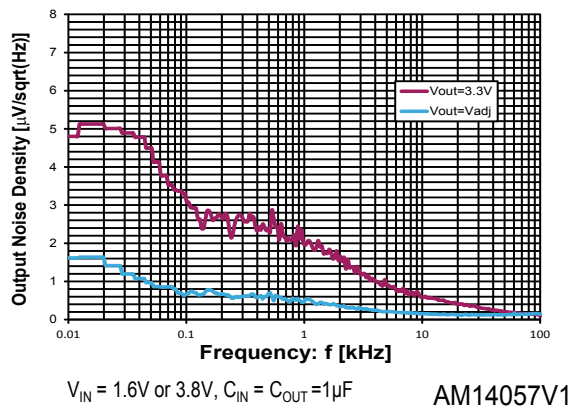
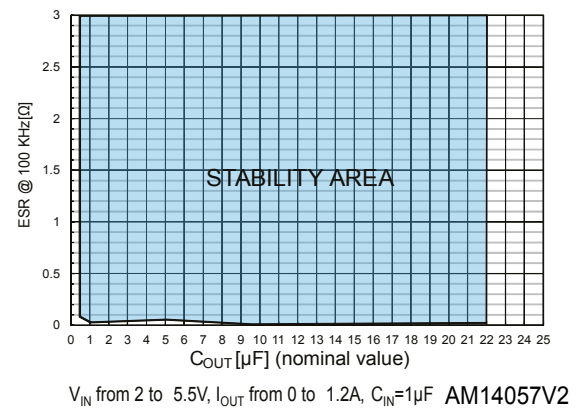
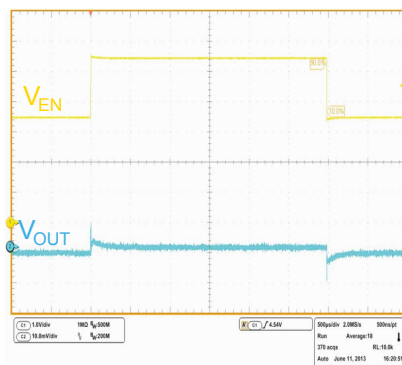
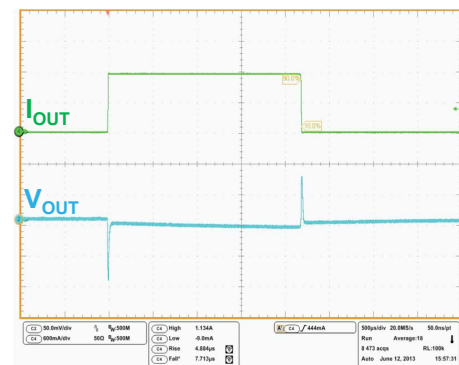
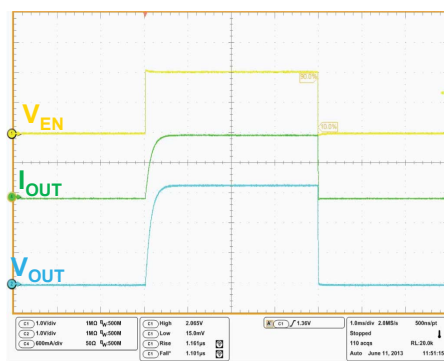
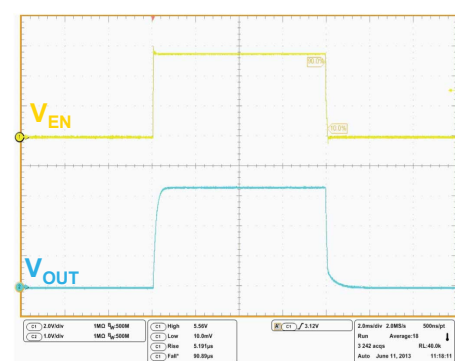
Figure 18. Dropout voltage vs. temperature
 $(I_{OUT} = 600 \text{ mA})$

Figure 19. Dropout voltage vs. temperature
 $(I_{OUT} = 1.2 A)$

Figure 20. Dropout voltage vs. load current

Figure 21. Short-circuit current vs. input voltage

Figure 22. Enable thresholds vs. temperature

Figure 23. SVR vs. frequency


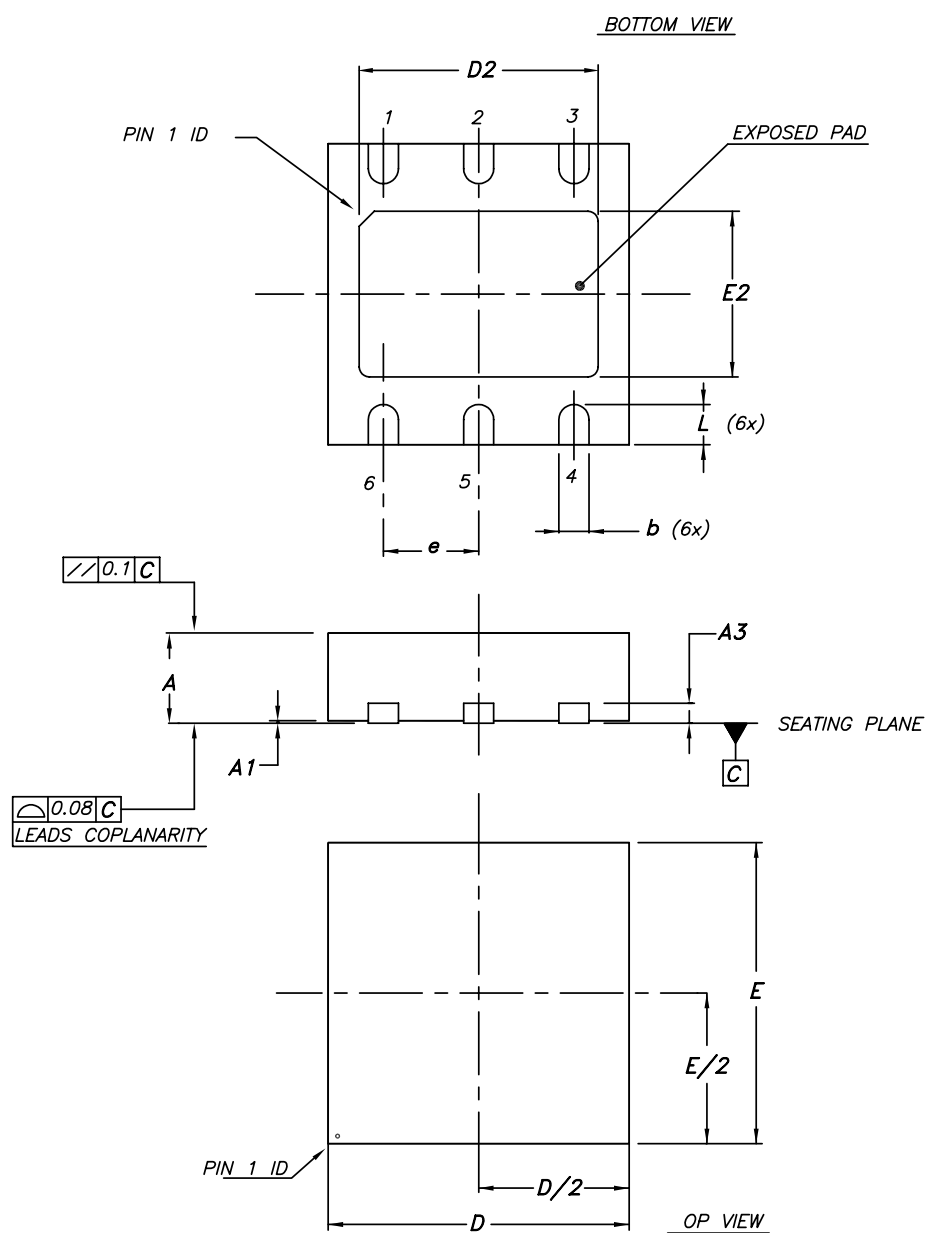
Figure 24. Output noise spectral density

Figure 25. Stability plan vs. C_{OUT} , ESR

Figure 26. Line transient

Figure 27. Load transient

Figure 28. Enable transient

Figure 29. Turn-on time


8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

8.1 DFN6 (3x3) package information

Figure 30. DFN6 (3x3) package outline



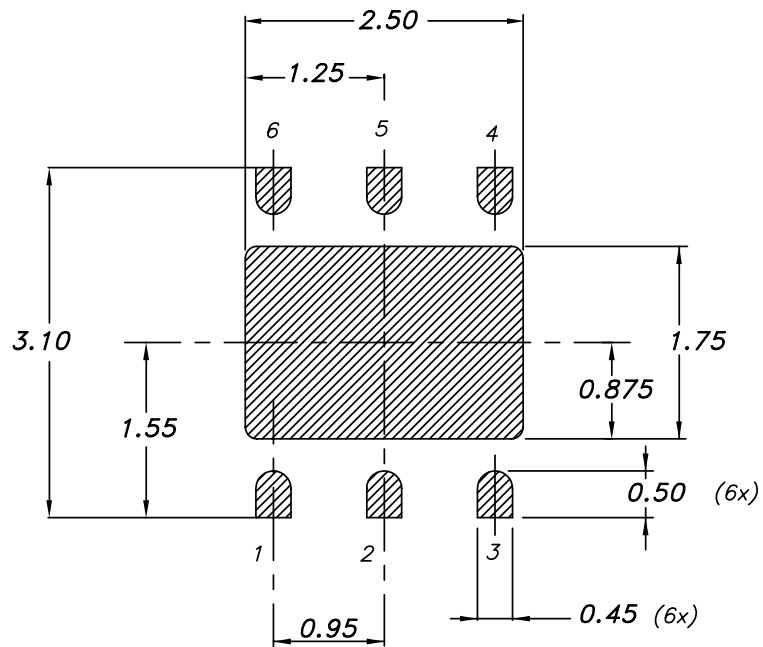
7946637_C

Table 6. DFN6 (3x3) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1
A1	0	0.02	0.05
A3		0.20	
b	0.23		0.45
D	2.90	3	3.10
D2	2.23		2.50
E	2.90	3	3.10
E2	1.50		1.75
e		0.95	
L	0.30	0.40	0.50

Figure 31. DFN6 (3x3) recommended footprint

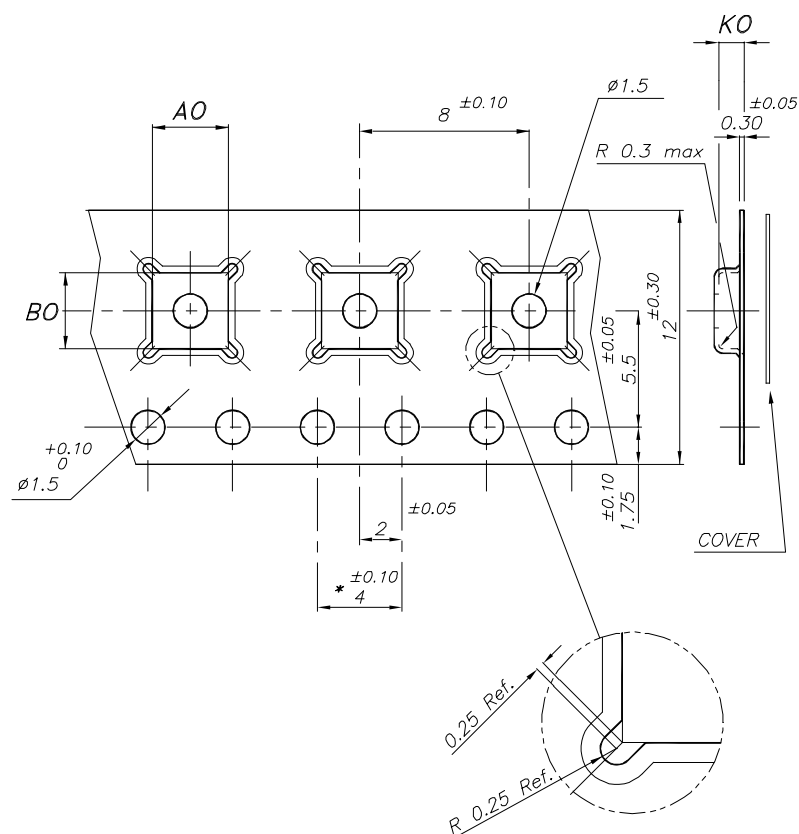
FOOTPRINT RECOMMENDED



7946637_C

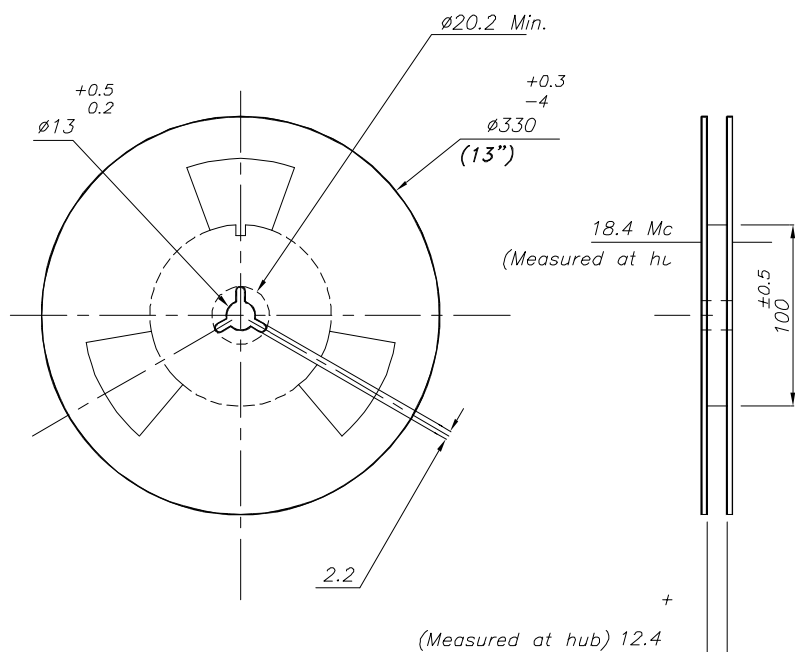
8.2 DFN6 (3x3) packing information

Figure 32. DFN6 (3x3) tape outline



*
- 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ± 0.20

7875978_N

Figure 33. DFN6 (3x3) reel outline


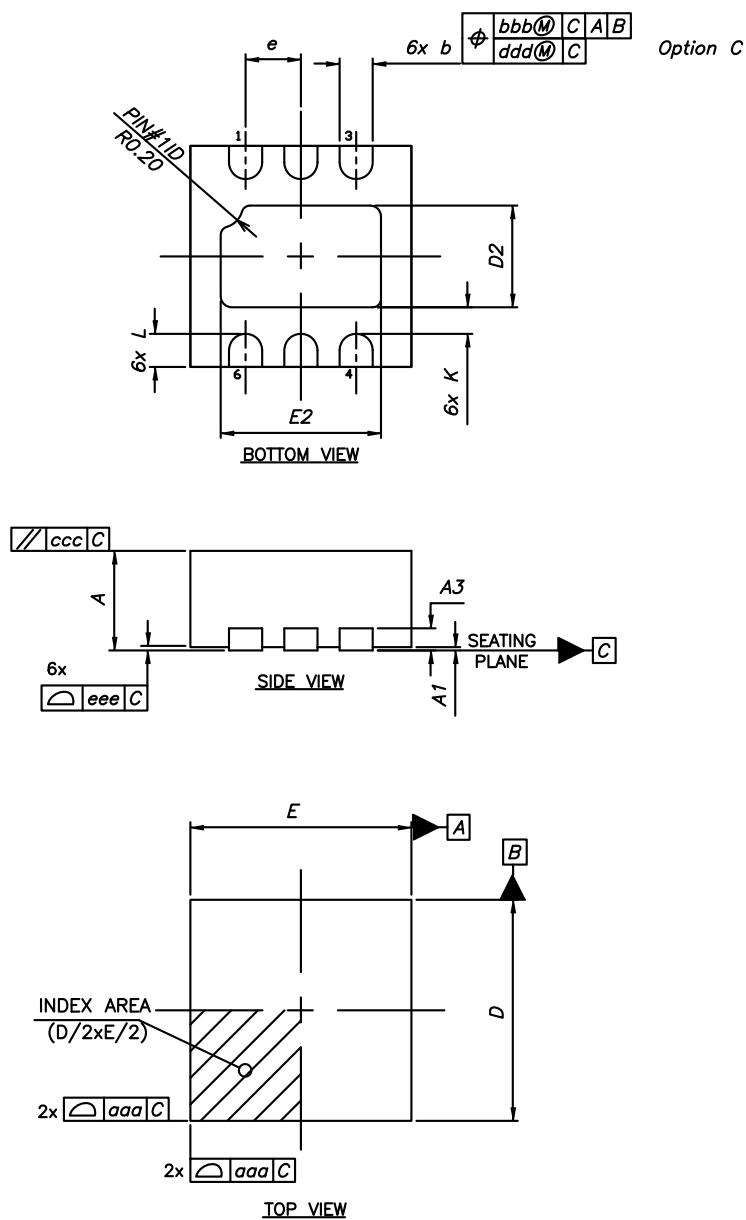
7875978_N

Table 7. DFN6 (3x3) tape and reel mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A0	3.20	3.30	3.40
B0	3.20	3.30	3.40
K0	1	1.10	1.20

8.3 DFN6 (2x2) package information

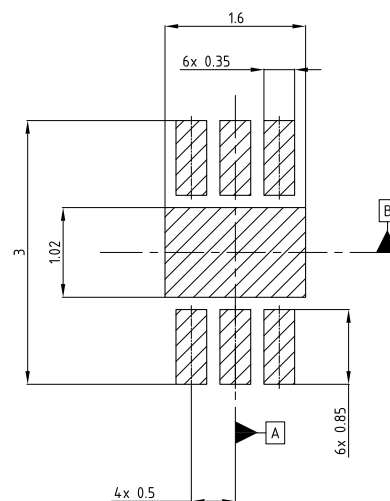
Figure 34. DFN6 (2x2) package outline



7733060

Table 8. DFN6 (2x2) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	-	0.203 ref	-
b	0.25	0.30	0.35
D	-	2.00	-
E	-	2.00	-
e	-	0.50	-
D2	0.77	0.92	1.02
E2	1.30	1.45	1.55
K	0.15	-	-
L	0.20	0.30	0.40
aaa	-	0.05	-
bbb	-	0.10	-
ccc	-	0.10	-
ddd	-	0.05	-
eee	-	0.08	-

Figure 35. DFN6 (2x2) recommended footprint


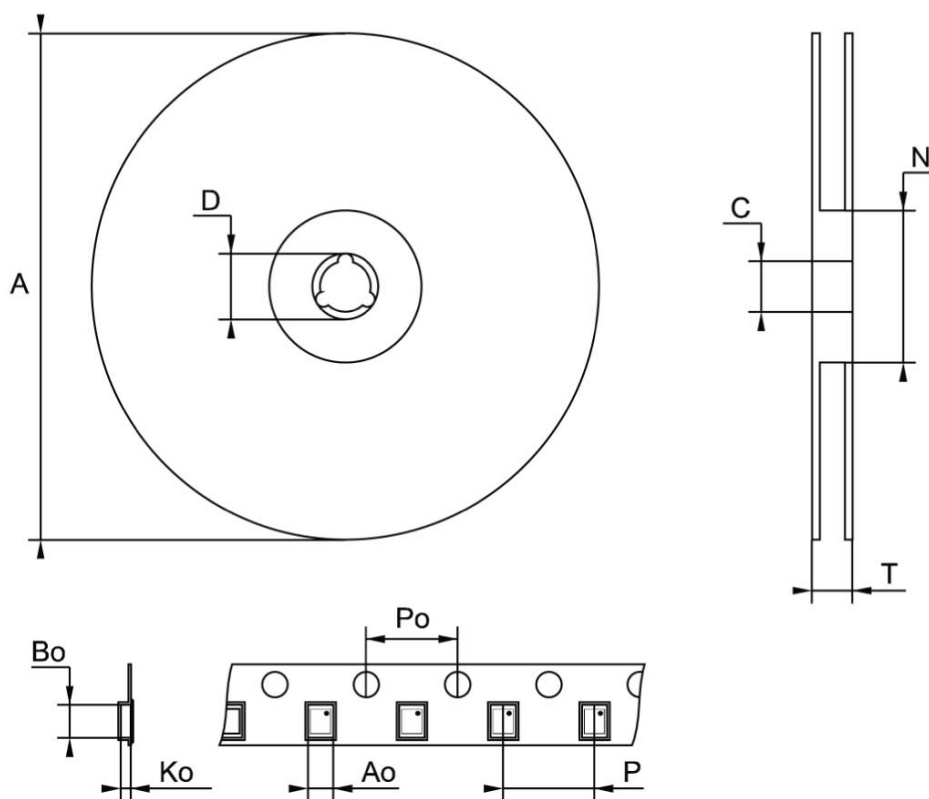
Notes:

- 1) This footprint is able to ensure insulation up to 32 Vrms (according to CEI IEC 664-1)
- 2) The device must be positioned within $\oplus 0.02$ A B

7733060 revE

8.4 DFN6 (2x2) packing information

Figure 36. DFN6 (2 x 2 mm) reel outline



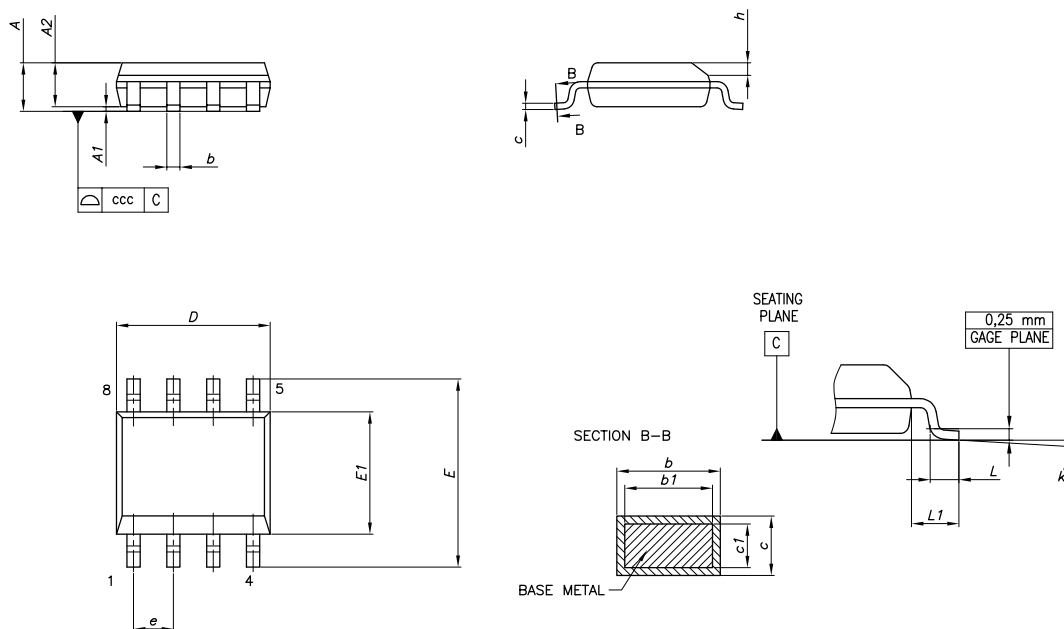
Note: Drawing not in scale

Table 9. DFN6 (2 x 2 mm) tape and reel mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			180
C	12.8		13.2
D	20.2		
N	60		
T			14.4
A0		2.4	
B0		2.4	
K0		1.3	
P0		4	
P		4	

8.5 SO8 package information

Figure 37. SO-8 batwing package outline

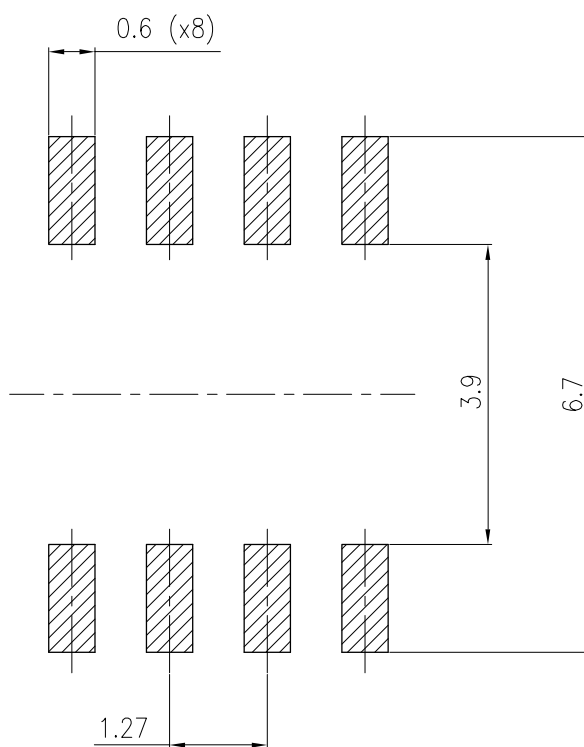


0016023_G

Table 10. SO-8 batwing mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
c	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

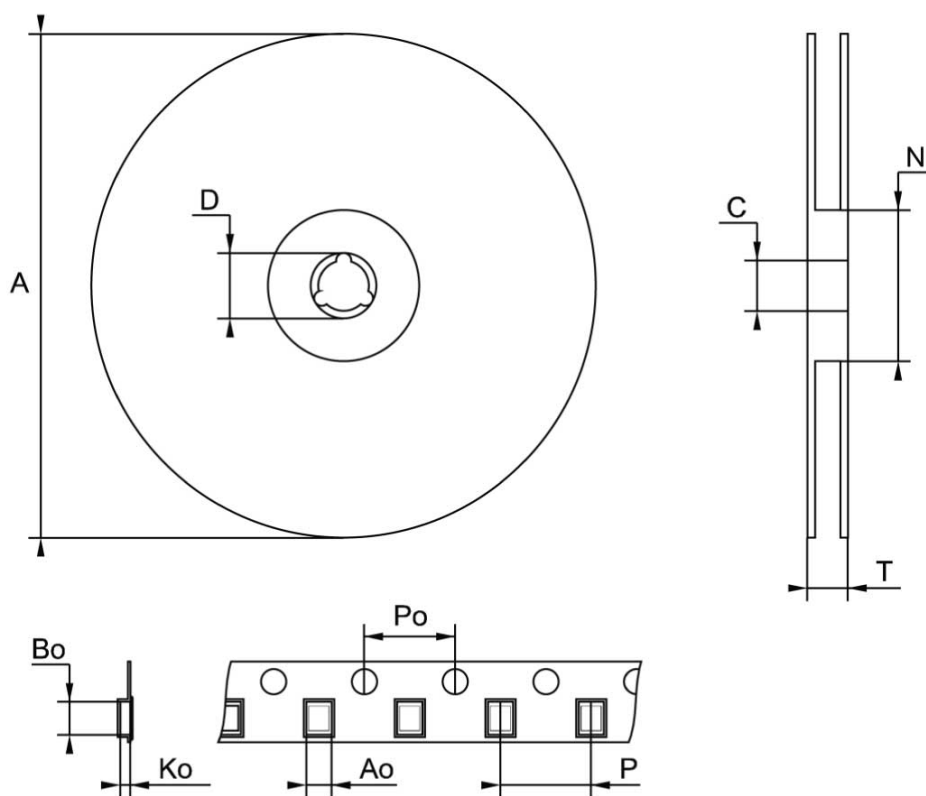
Figure 38. SO-8 batwing recommended footprint



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8.6 SO8-batwing packing information

Figure 39. SO8-batwing tape and reel outline



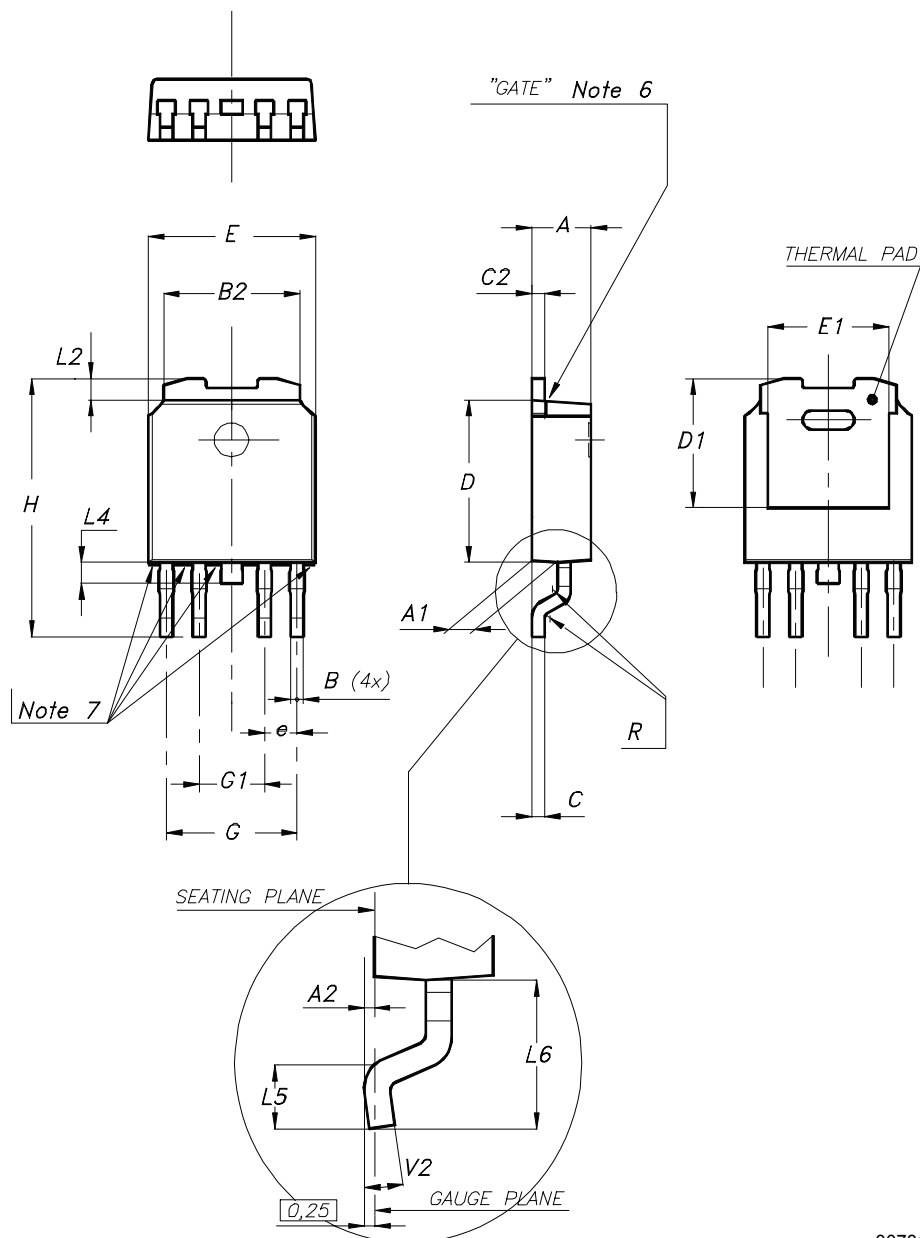
Note: Drawing not in scale

Table 11. SO8-batwing mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			330
C	12.8		13.2
D	20.2		
N	60		
T			22.4
A0	8.1		8.5
B0	5.5		5.9
K0	2.1		2.3
P0	3.9		4.1
P	7.9		8.1

8.7 PPAK package information

Figure 40. PPAK package outline



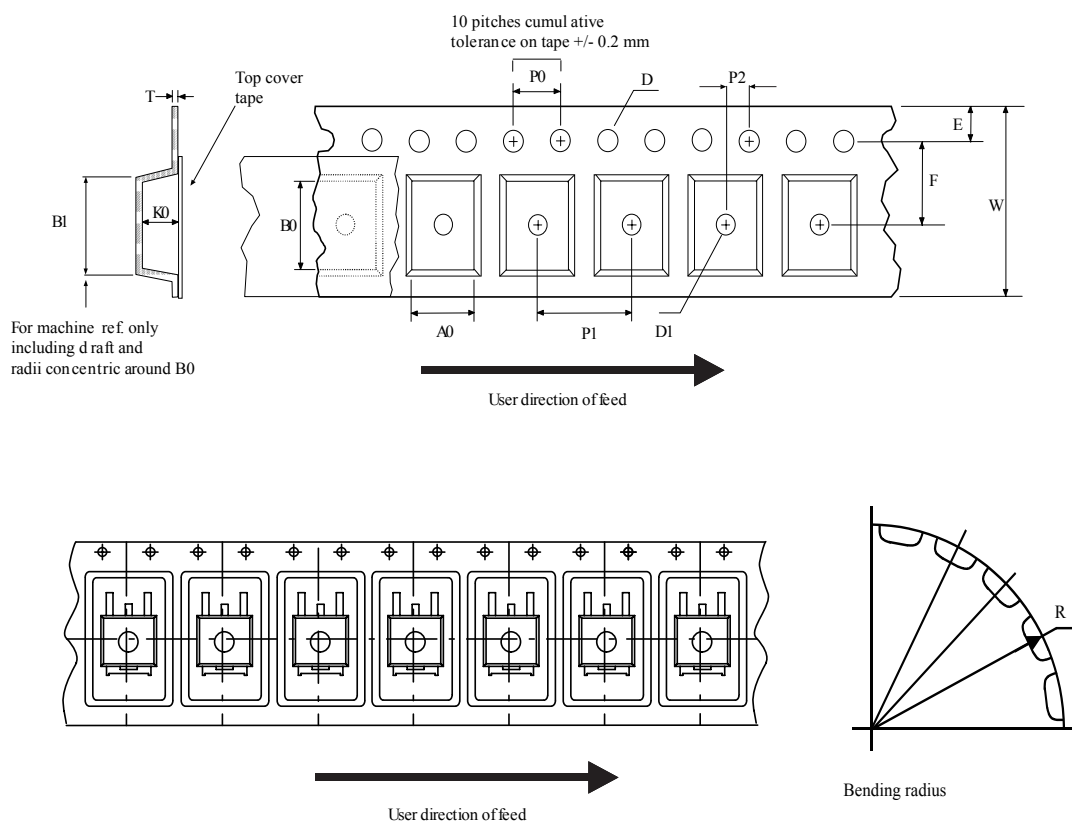
0078180_F

Table 12. PPAK mechanical data

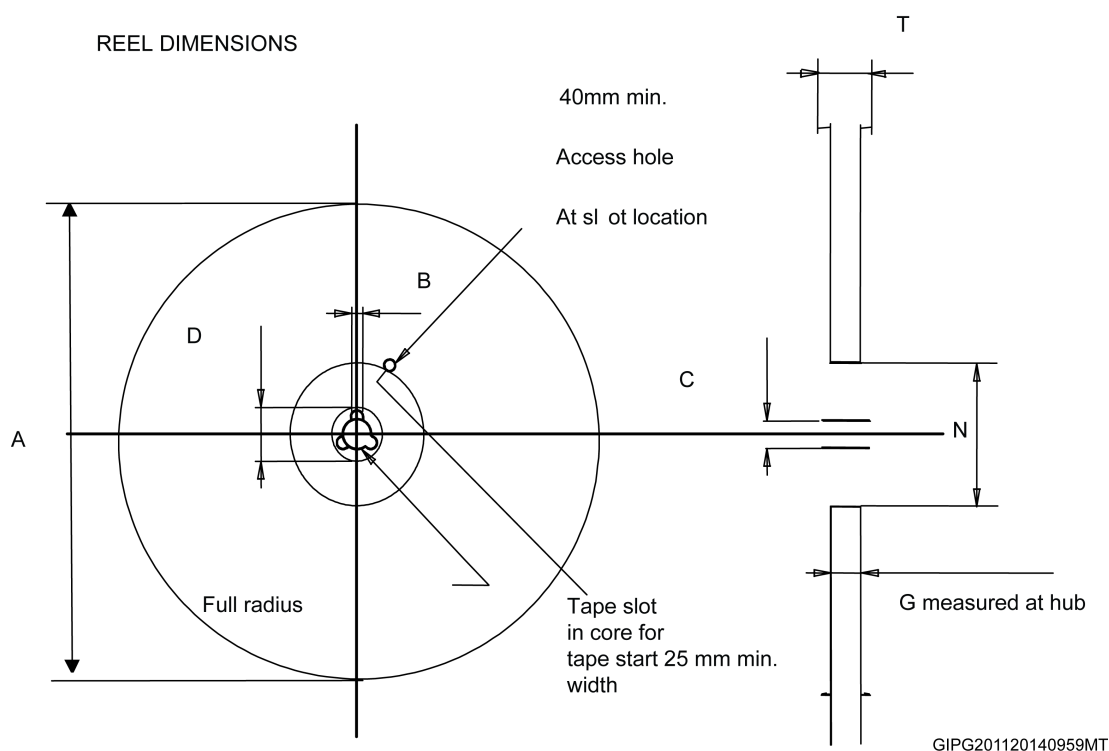
Dim.	mm		
	Min.	Typ.	Max.
A	2.2		2.4
A1	0.9		1.1
A2	0.03		0.23
B	0.4		0.6
B2	5.2		5.4
C	0.45		0.6
C2	0.48		0.6
D	6		6.2
D1		5.1	
E	6.4		6.6
E1		4.7	
e		1.27	
G	4.9		5.25
G1	2.38		2.7
H	9.35		10.1
L2		0.8	1
L4	0.6		1
L5	1		
L6		2.8	
R		0.20	
V2	0°		8°

8.8 PPAK packing information

Figure 41. PPAK tape outline



AM08852v1

Figure 42. PPAK reel outline

Table 13. PPAK mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Base qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

9 Ordering information

Table 14. Order codes

DFN6 (3x3)	DFN6 (2x2)	SO8-batwing	PPAK	Output voltage (V)
LDL112PV10R	LDL112PU10R	LDL112D10R		1.0
LDL112PV12R	LDL112PU12R	LDL112D12R		1.2
LDL112PV15R				1.5
LDL112PV18R	LDL112PU18R	LDL112D18R		1.8
	LDL112PU30R			3.0
LDL112PV33R	LDL112PU33R	LDL112D33R		3.3
LDL112PVR	LDL112PUR	LDL112DR	LDL112PT-TR	Adj

Revision history

Table 15. Document revision history

Date	Revision	Changes
21-Nov-2014	1	Initial release.
28-Oct-2016	2	Updated Figure 32. DFN6 (2x2) package outline. Modified Table 9. Order codes. Minor text changes.
20-Feb-2019	3	Updated Table 14 . Order codes .

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